

Pb Free Terminal Finish.

ULTRAFAST SOFT RECOVERY RECTIFIER DIODE

PRODUCT APPLICATIONS

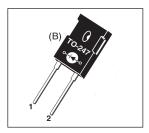
- Anti-Parallel Diode
 - -Switchmode Power Supply -Inverters
- Free Wheeling Diode
 - -Motor Controllers
 - -Converters
 - -Inverters
- Snubber Diode
- PFC

PRODUCT FEATURES

- Ultrafast Recovery Times
- Soft Recovery Characteristics
- Popular TO-247 Package
- · Low Forward Voltage
- Low Leakage Current

PRODUCT BENEFITS

- Low Losses
- . Low Noise Switching
- Cooler Operation
- . Higher Reliability Systems
- Increased System Power Density





- 1 Cathode
- 2 Anode
 - Back of Case Cathode

MAXIMUM RATINGS

All Ratings: T_C = 25°C unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT15D60BG	UNIT
V _R	Maximum D.C. Reverse Voltage		
V _{RRM}	Maximum Peak Repetitive Reverse Voltage	600	Volts
V _{RWM}	Maximum Working Peak Reverse Voltage		
I _{F(AV)}	Maximum Average Forward Current (T _C = 133°C, Duty Cycle = 0.5)	15	
I _{F(RMS)}	RMS Forward Current (Square wave, 50% duty)	32	Amps
I _{FSM}	Non-Repetitive Forward Surge Current (T _J = 45°C, 8.3ms)	110	
T _J ,T _{STG}	Operating and StorageTemperature Range	-55 to 175	°C
T _L	Lead Temperature for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

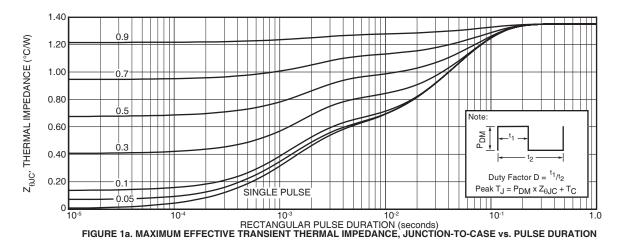
Symbol	Characteristic / Test Conditions		MIN	TYP	MAX	UNIT
V _F	Forward Voltage	I _F = 15A		1.6	1.8	Volts
		I _F = 30A		1.9		
		I _F = 15A, T _J = 125°C		1.4		
I _{RM}	Maximum Reverse Leakage Current	V _R = V _R Rated			150	μΑ
		$V_R = V_R$ Rated, $T_J = 125$ °C			500	
C _T	Junction Capacitance, V _R = 200V			23		pF

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
t _{rr}	Reverse Recovery Time I _F = 1A, di _F /dt =	/dt = -100A/ μ s, V _R = 30V, T _J = 25°C		21		20
t _{rr}	Reverse Recovery Time	$I_F = 15A$, $di_F/dt = -200A/\mu s$ $V_R = 400V$, $T_C = 25^{\circ}C$	-	80		ns
Q _{rr}	Reverse Recovery Charge		-	95		nC
I _{RRM}	Maximum Reverse Recovery Current		-	3	-	Amps
t _{rr}	Reverse Recovery Time	$I_F = 15A$, $di_F/dt = -200A/\mu s$ $V_R = 400V$, $T_C = 125°C$	-	150		ns
Q _{rr}	Reverse Recovery Charge		-	520		nC
I _{RRM}	Maximum Reverse Recovery Current		-	7	-	Amps
t _{rr}	Reverse Recovery Time	$I_F = 15A$, $di_F/dt = -1000A/\mu s$ $V_R = 400V$, $T_C = 125°C$	-	60		ns
Q _{rr}	Reverse Recovery Charge		-	810		nC
I _{RRM}	Maximum Reverse Recovery Current		-	22		Amps

THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			1.35	°C/W
$R_{ hetaJA}$	Junction-to-Ambient Thermal Resistance			40	
W _T	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb•in
				1.1	N•m

APT Reserves the right to change, without notice, the specifications and information contained herein.



Junction temp (°C)

Power (watts)

0.583 °C/W

0.00222 J/°C

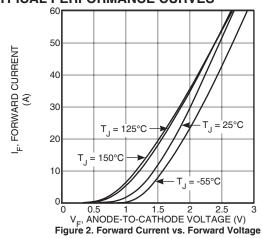
0.767 °C/W

0.0598 J/°C

Case temperature (°C)

FIGURE 1b, TRANSIENT THERMAL IMPEDANCE MODEL

TYPICAL PERFORMANCE CURVES



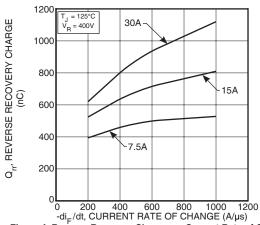
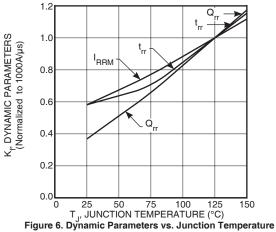
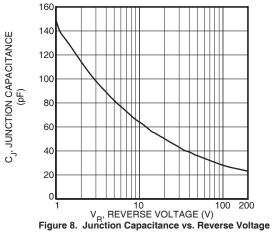


Figure 4. Reverse Recovery Charge vs. Current Rate of Change





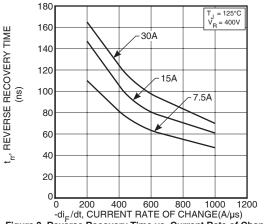


Figure 3. Reverse Recovery Time vs. Current Rate of Change

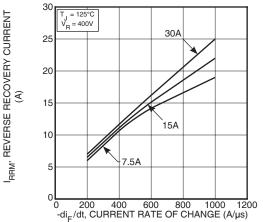


Figure 5. Reverse Recovery Current vs. Current Rate of Change

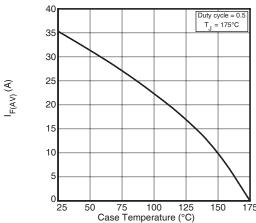


Figure 7. Maximum Average Forward Current vs. CaseTemperature

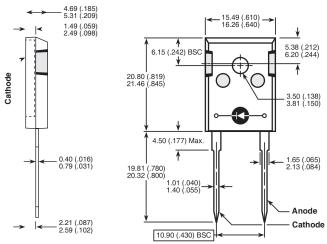
0.25 I_{RRM}

Figure 9. Diode Test Circuit

- 1 I_F Forward Conduction Current
- 2 di_E/dt Rate of Diode Current Change Through Zero Crossing.
- 3 I_{RRM} Maximum Reverse Recovery Current.
- 4 t_{rr} Reverse Recovery Time, measured from zero crossing where diode current goes from positive to negative, to the point at which the straight line through I_{RRM} and 0.25•I_{RRM} passes through zero.
- Q_{rr} Area Under the Curve Defined by I_{RRM} and t_{rr}.

Figure 10, Diode Reverse Recovery Waveform and Definitions

TO-247 Package Outline



Dimensions in Millimeters and (Inches)





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APT2X60D60J APT30DQ60BG APT40DQ60BG APT60DQ60BCTG APT2X61DQ60J APT30D60BCAG

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APT60D60LCTG APT2X60DQ60J APT30DQ60BCTG APT30DS60BG APT15DS60BG APT30D60SG

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APT100D60B2G APT100D60BG